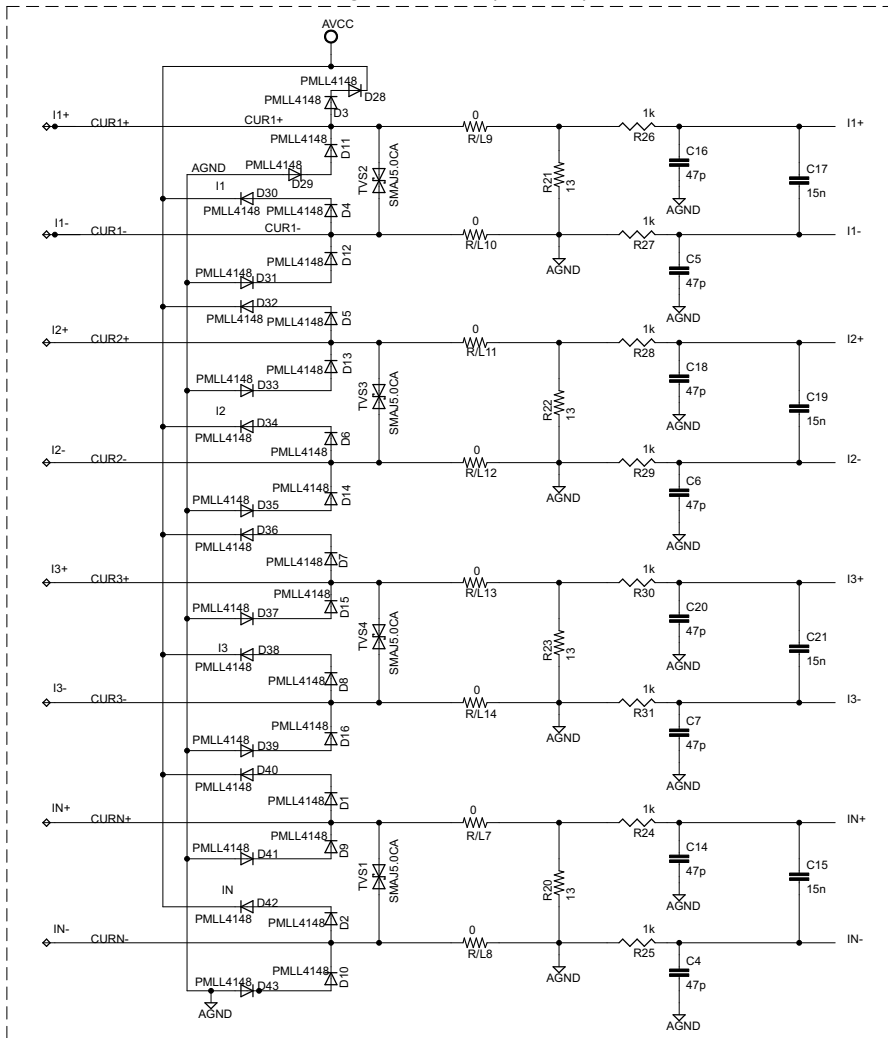
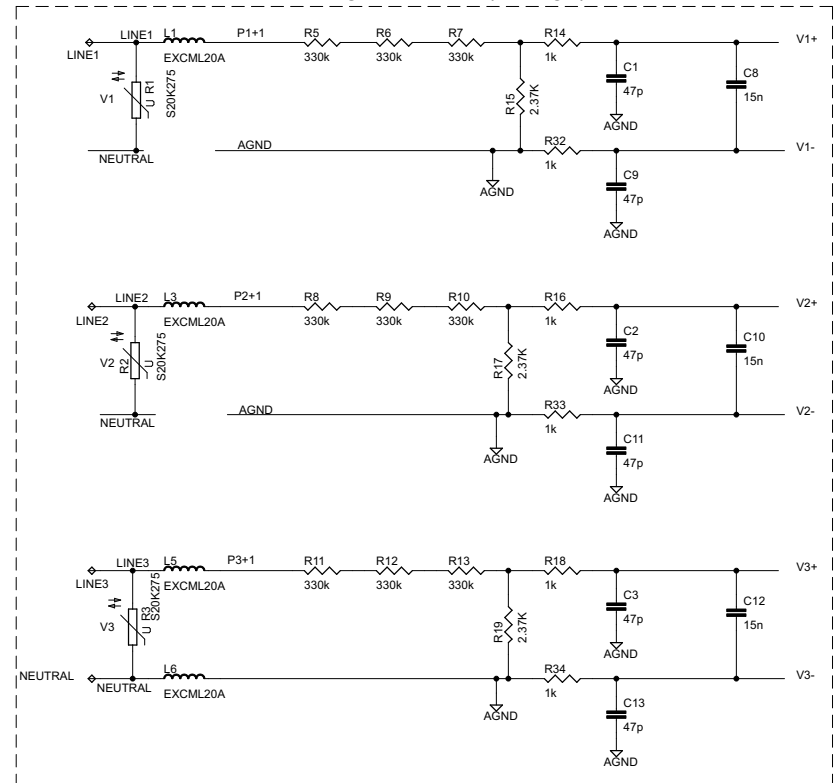


TIDC-3PHMTR-WIFIXR
(EVM430-f6779)

Analog Front-End (Current)

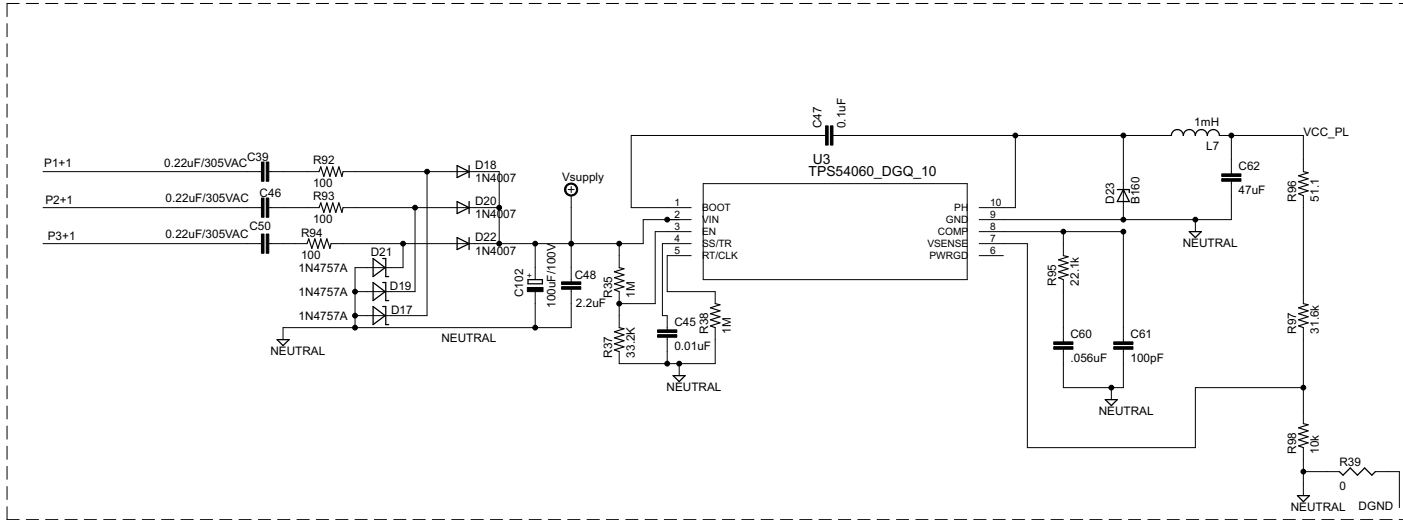


Analog Front-End (Voltage)

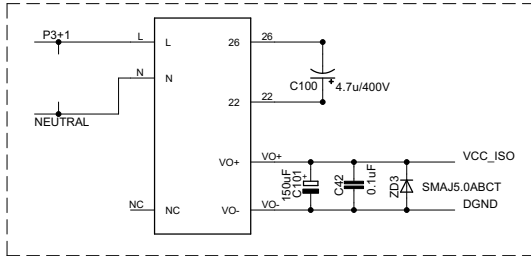


TIDC-3PHMTR-WIFXR
(EVM430-f6779)

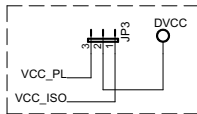
Un-isolated VCC from AC Mains



Isolated VCC from AC Mains

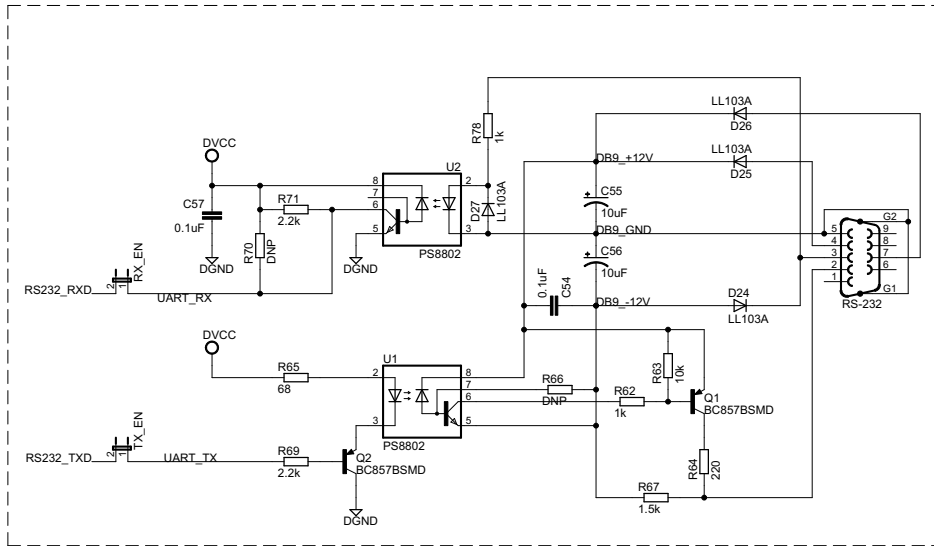


VCC Select

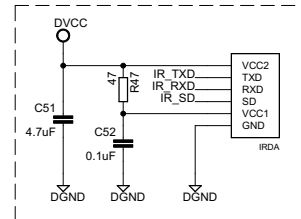


TIDC-3PHMTR-WIFIXR
(EVM430-f6779)

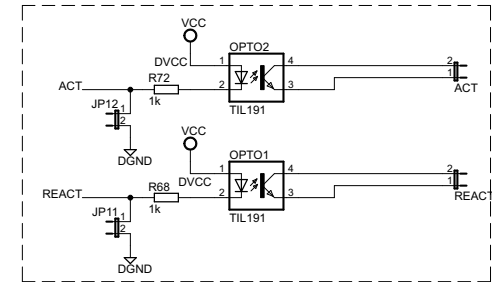
Isolated RS232 Communication



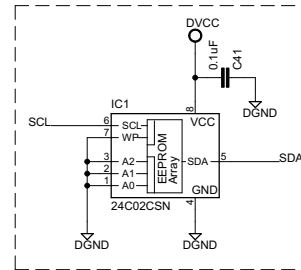
IR Pulse In/Out



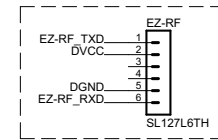
Act / React



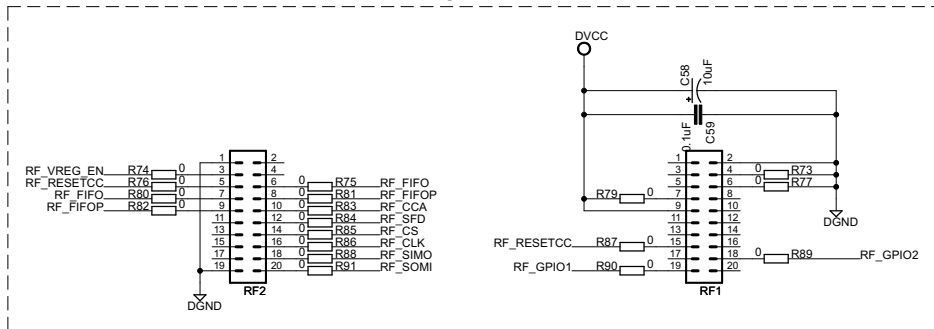
EEPROM



EZ-RF Connect

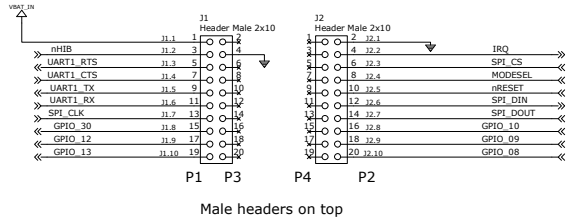


RF Daughter Card

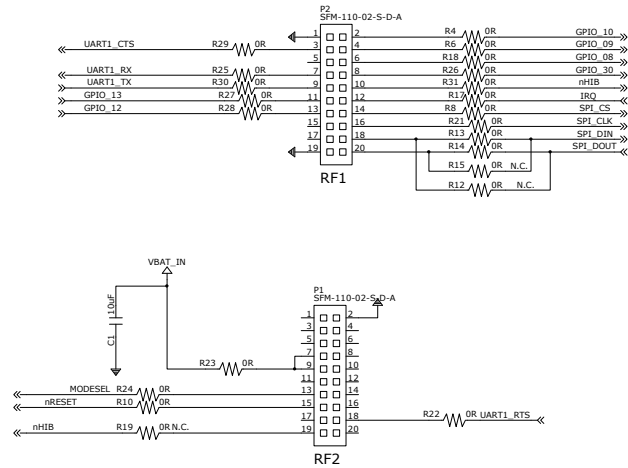


TIDC-3PHMTR-WIFIXR
(EVM430-f6779)

CC3100 Booster Pack Conn



EM connector



TIDC-3PHMTR-WIFIXR
(EM-BP ADAPTER)

Texas Instruments India Pvt. Ltd. Wireless Connectivity Solutions Business Unit (WCS)		Tel: +91-80-2534-5454, Fax: +91-80-2504-8308		Bagmane Tech Park, Bangalore, 560093, INDIA	
		Approval	Date	Project Title	
Drawn by	04/11/12	EM-BP_ADAPTER			
Board Owner	04/11/12	Size	Project Number	Revision	
Engineering	04/11/12	Date	7/2/2013	6:29:39 PM	Sheet 01 of 01

Revision History

Rev 2.0-B

First draft

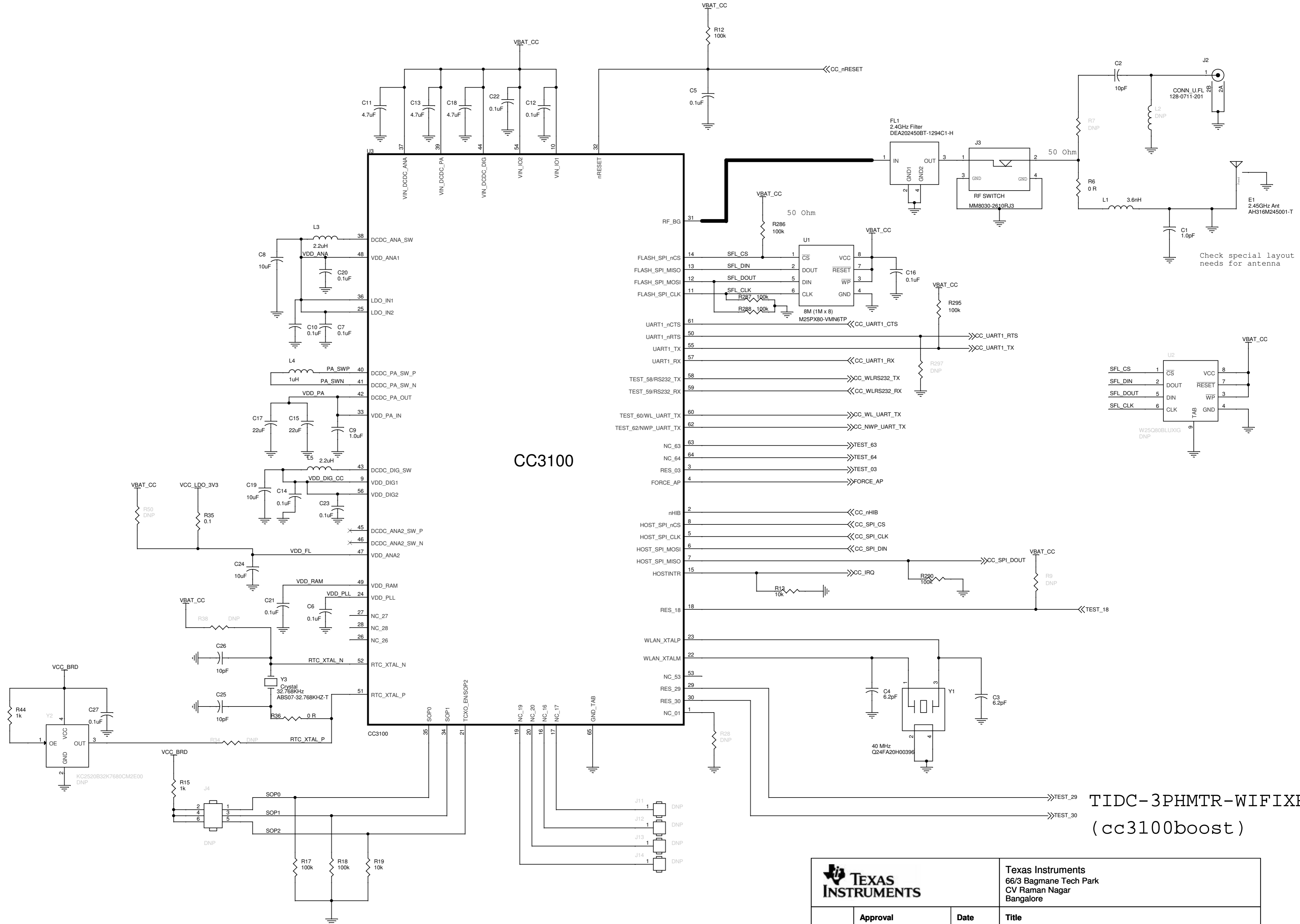
Rev 3.3-A

1. Added push button for nHIB
2. Added Murata Connector for RF test
3. Added LED for nRESET
4. Routed the VDD_FLASH to 3.3V
5. Moved the 100uF cap from VCC_BRD to VBAT_CC. Changed cap to 100uF ceramic from Tantalum
6. Removed 0.1 Ohm resistor for current measurement by default
7. Removed RS232 UART connection by default

Rev 4.0-A

=====

1. Added pull-up/down resistors for the serial flash
2. Added pulls for all floating output pins
3. Re-assigned J5 for nHIB for use in OOB demo
4. Modified R12 to from 10K to 100K
5. R13 is changed from 3.3K to 10K



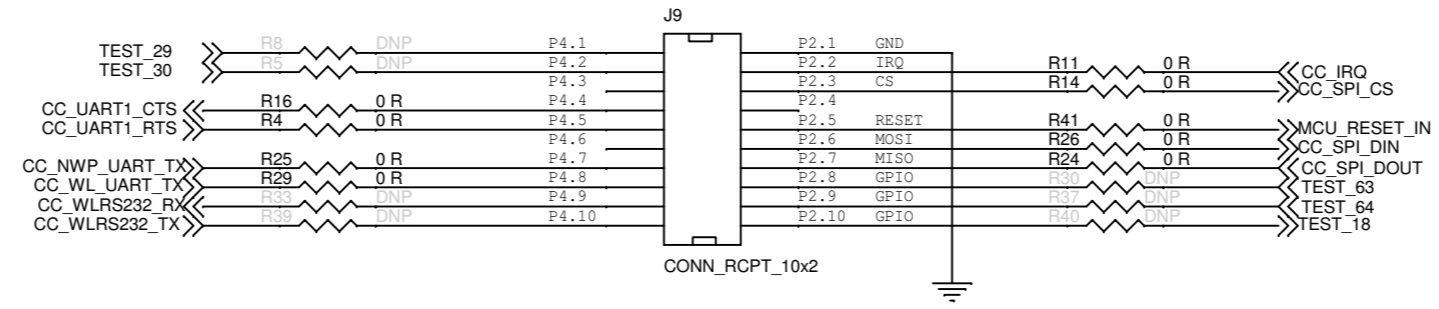
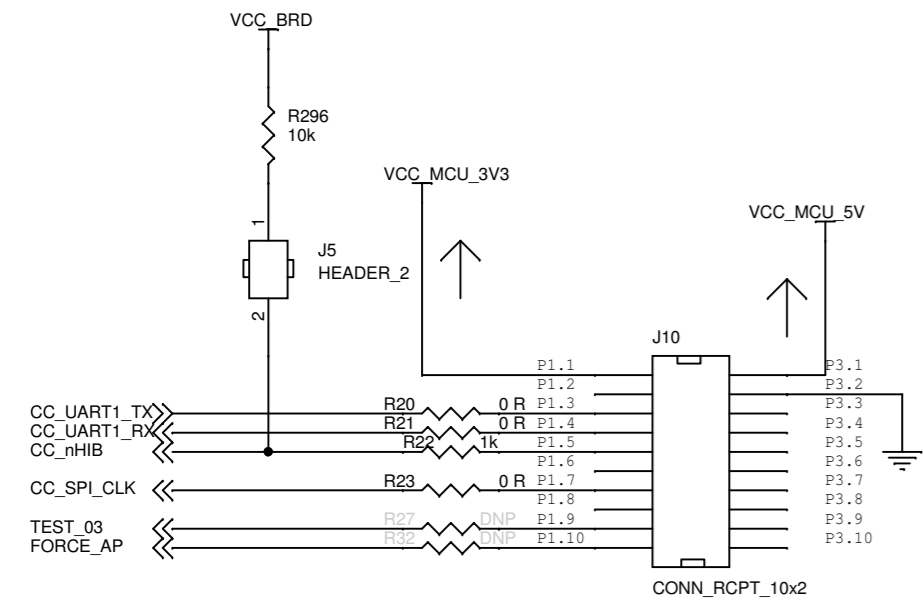
CC3100

TIDC-3PHMTR-WIFIXR
(cc3100boost)

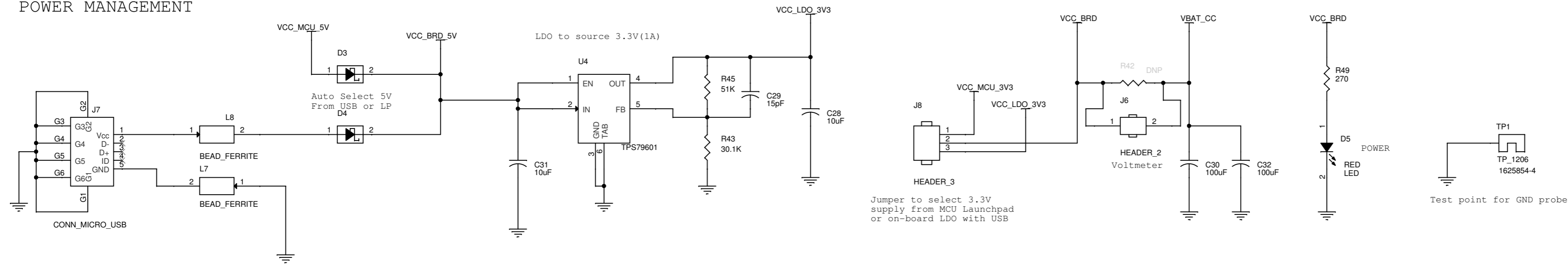
TEXAS INSTRUMENTS
Texas Instruments
66/3 Bagmane Tech Park
CV Raman Nagar
Bangalore

Approval		Date	Title		
Designer	TI	Date	CC3100BOOST		
Drawn By	TI	Date	Size A2	Project No <Project Number>	Rev 4.0- A
Layout	TI	Date	Scale	Date Thursday, June 05, 2014	Sheet 1 of 3

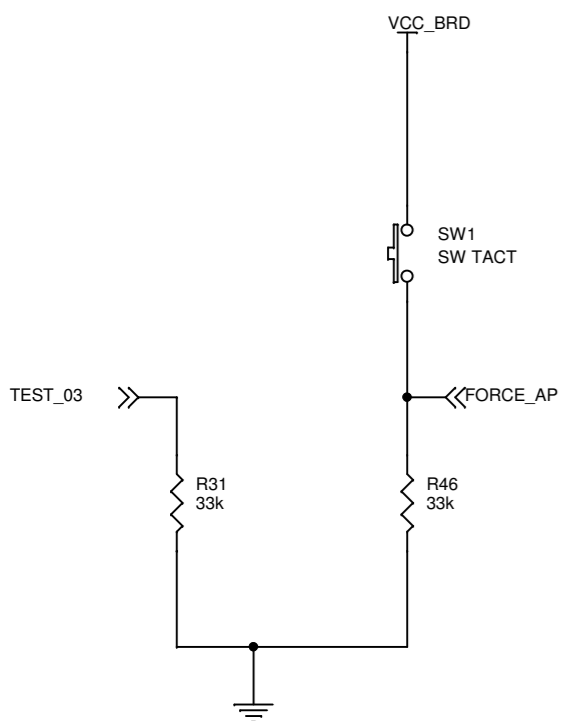
LAUNCHPAD INTERFACE



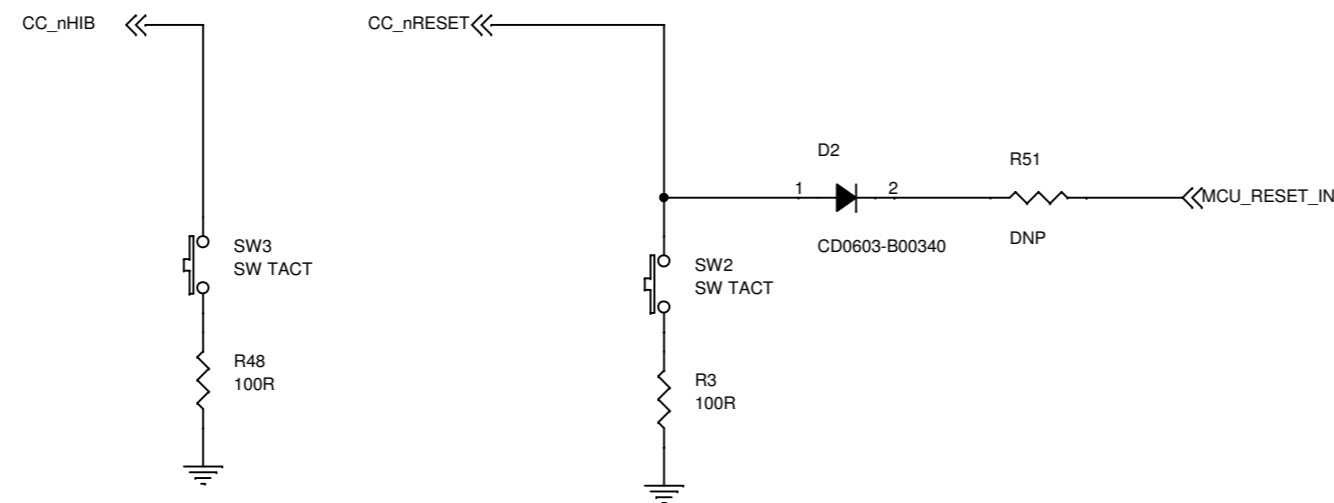
POWER MANAGEMENT



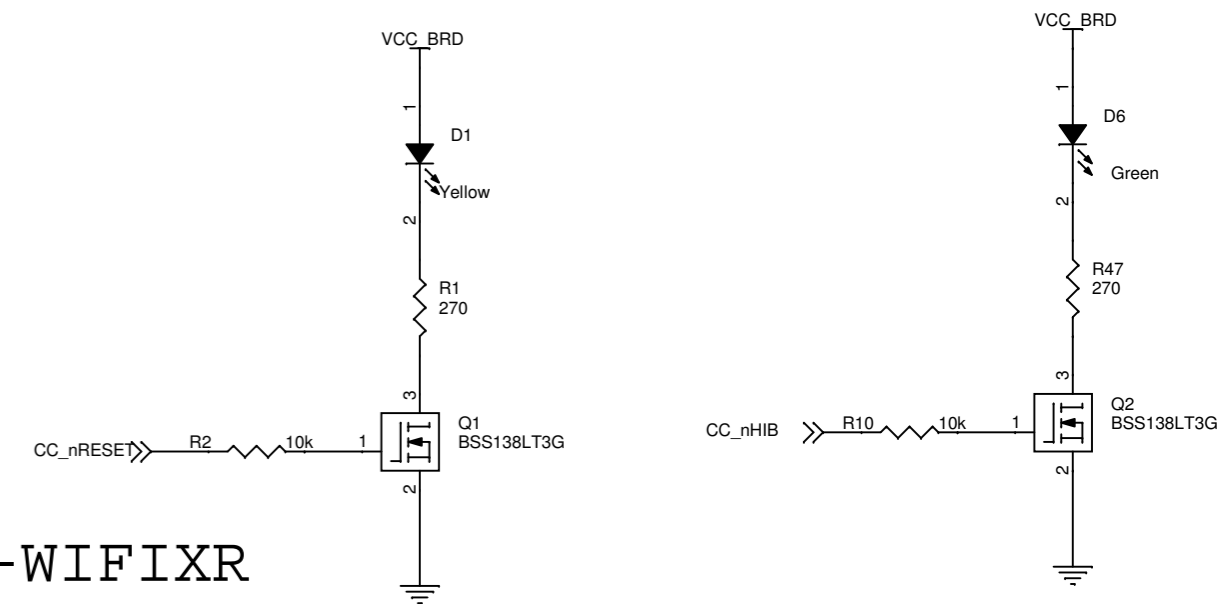
OOB DEMO



PUSH BUTTONS



LEDs



TIDC-3PHMTR-WIFIXR (cc3100boost)

		Texas Instruments 66/3 Bagmane Tech Park CV Raman Nagar Bangalore		
Approval	Date	Title CC3100BOOST		
Designer	Texas Instruments	Date		
Drawn By	TI	Date	Size A2	Project No <Project Number>
Layout	TI	Date	Scale	Rev 4.0A
			Date	Thursday, June 05, 2014
			Sheet 2 of 3	

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